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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Grigg et al.

Serial No.: 10/688,354

Filed: October 17, 2003

For: THICK SOLDER MASK FOR
CONFINING ENCAPSULANT MATERIAL
OVER SELECTED LOCATIONS OF A
SUBSTRATE AND ASSEMBLIES
INCLUDING THE SOLDER MASK

Confirmation No.: 2306

Examiner: C. Wilson

Group Art Unit: 2891

Attorney Docket No.: 2269-5216.1US
(99-0507.01/US)

Notice of Allowance Mailed:

January 3, 2006

NOTICE OF EXPRESS MAILING

Express Mail Mailing Label Number: EL995990072US

Date of Deposit with USPS: April 3, 2006

Person making Deposit: Timothy Palfreyman

AMENDMENT PURSUANT TO 37 C.F.R. § 1.312(a)

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Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

Sir:

Please amend the above-referenced application as follows: